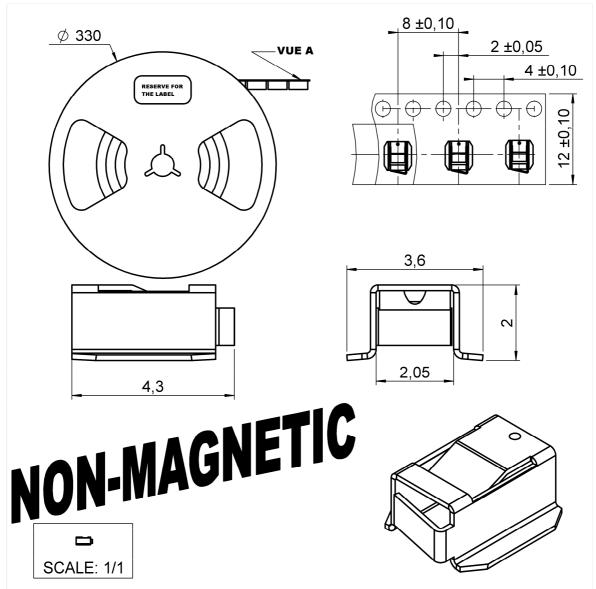

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REEL 4000

Series: UMP



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BERYLLIUM COPPER	TIN

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In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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REEL 4000

Series: UMP

PACKAGING

Standard Unit Other 4000 Contact us

SPECIFICATION

PAQP-VOR-017

ELECTRICAL CHARACTERISTICS

Impedance 50Ω

Frequency **0-6** GHz

VSWR 1.05 + 0,0300 x F(GHz) Maxi Insertion loss NA $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz)) dB Maxi Voltage rating 100 Veff Maxi Dielectric withstanding voltage Insulation resistance 350 Veff mini 1000 $M\Omega$ mini

ENVIRONMENTAL

Operating temperature -40/+55 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

Magnetic field distorsion

< 0.5 ppm at 10 mm at Bo=1.5 Tesla

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end - N mini
Axial force – Opposite end - N mini
Torque - N.cm mini

Recommended torque

Mating - N.cm
Panel nut - N.cm

Mating life 100 Cycles mini

Weight **0,0300** g

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REEL 4000 Series: UMP

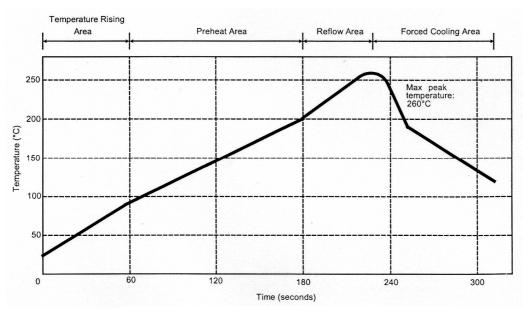
SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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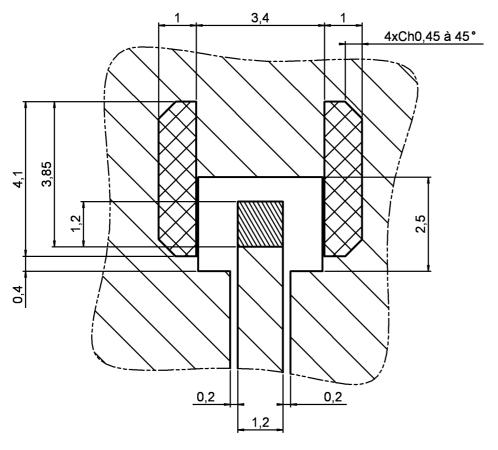
UMP SERIES INFORMATION

PCB

COPLANAR LINE

Ground and signal are on the same side

Thickness of PCB:1 mm



18 μ m Cu mini + 7 to 9 μ m Sn

18μm Cu mini + 7 to 9 μm Sn

Ground + varnish

The material of PCB is glass-epoxy Composite. (Er=4.8)

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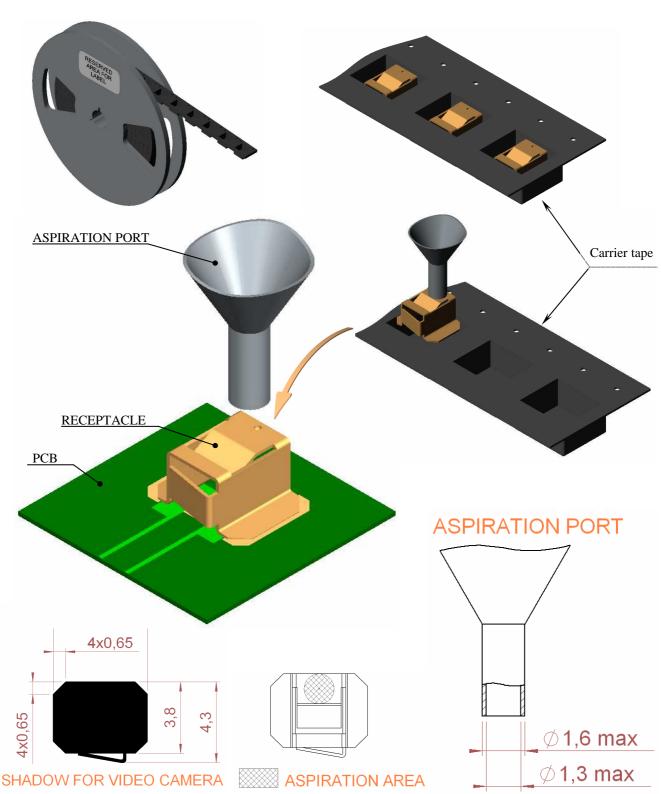


Series: UMP

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REEL 4000

UMP SERIES INFORMATION



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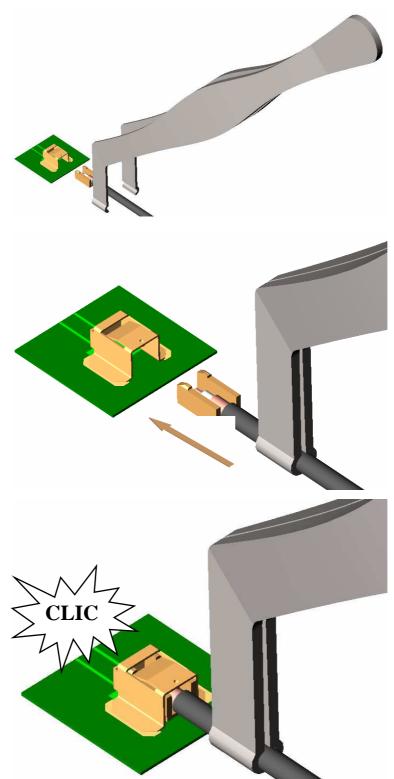


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REEL 4000

Series: UMP

UMP CONNECTING NOTE



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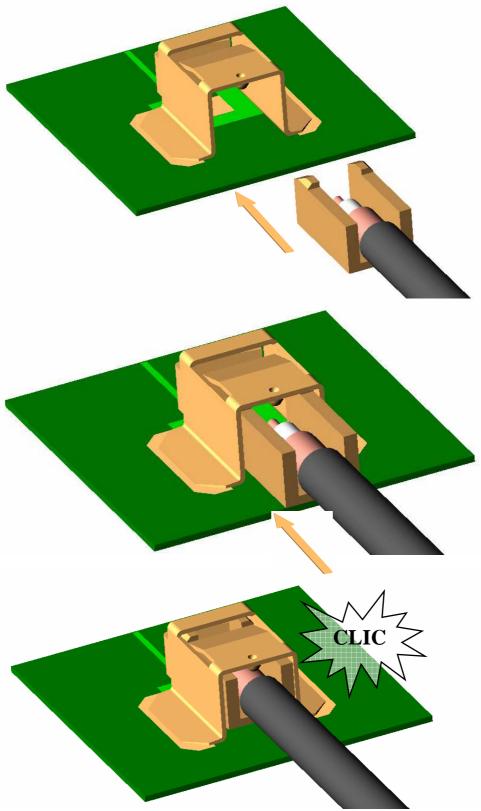


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UMP CONNECTING NOTE



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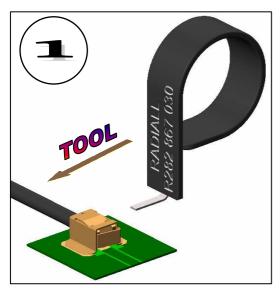


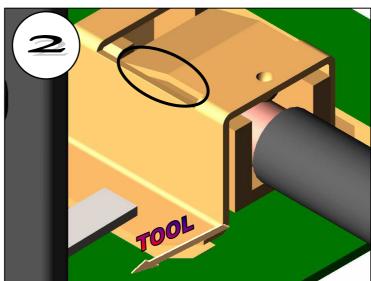
R107.003.097

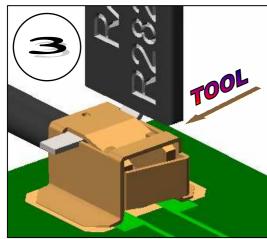
REEL 4000

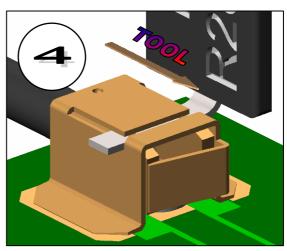
Series: UMP

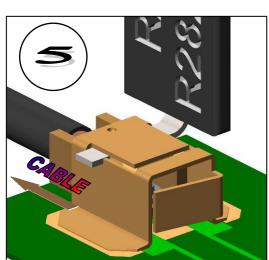
UMP DISCONNECTING NOTE

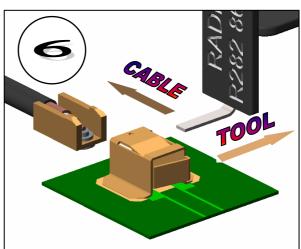












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